



Title of Change:	Addition of wafer fabrication site to United Microelectronics Corp, USA for wafer fab.													
Proposed First Ship date:	17 February 2020													
Contact Information:	Contact your local ON Semiconductor Sales Office or <Osamu.Akaki@onsemi.com>													
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.Samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.													
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>													
Change Part Identification:	It can be identified by lot number.													
Change Category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____													
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____													
Sites Affected:	ON Semiconductor Sites: ON Aizu, Japan	External Foundry/Subcon Sites: Foundry : United Microelectronics Corp, USA												
Description and Purpose: This initial Product/Process Change Notification (IPCN) announces the fab transfer of UMC for wafer process. Niigata for Back grind (BG) and Back metal (BM) process and ONSC for assembly process are not changed.														
<table border="1"> <thead> <tr> <th>Process</th> <th>Before Change Description</th> <th colspan="2">After Change Description</th> </tr> </thead> <tbody> <tr> <td>Wafer fab</td> <td>ON Aizu, Japan</td> <td>ON Aizu, Japan</td> <td rowspan="2">United Microelectronics Corp, USA</td> </tr> <tr> <td>UBM</td> <td>JX Nippon Mining & Metals Corporation, Japan</td> <td>JX Nippon Mining & Metals Corporation, Japan</td> </tr> </tbody> </table>				Process	Before Change Description	After Change Description		Wafer fab	ON Aizu, Japan	ON Aizu, Japan	United Microelectronics Corp, USA	UBM	JX Nippon Mining & Metals Corporation, Japan	JX Nippon Mining & Metals Corporation, Japan
Process	Before Change Description	After Change Description												
Wafer fab	ON Aizu, Japan	ON Aizu, Japan	United Microelectronics Corp, USA											
UBM	JX Nippon Mining & Metals Corporation, Japan	JX Nippon Mining & Metals Corporation, Japan												
There is no product marking change as a result of this change.														

**Qualification Plan:****QV DEVICE NAME:** EFC2K103NUZTDG**RMS:** S50064**PACKAGE:** WLCSP

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1,008 hrs
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1,008 hrs
HTSL	JESD22-A103	Ta= 150°C	1,008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15,000 cyc
TC	JESD22-A104	Ta= -40°C to +125°C	1,000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
UHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
LTSL	JESD22-A119	Ta=-55°C	1,008hrs

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

Part Number	Qualification Vehicle
EFC2K103NUZTDG	EFC2K103NUZTDG
EFC2K102NUZTDG	EFC2K103NUZTDG